



DMN39M1LK3

Product Summary

BV _{DSS}	Rds(on) Max	I _D Max T _C = +25°C
30V	5.5mΩ @ V _{GS} = 10V	89A
	9.0mΩ @ V _{GS} = 4.5V	69A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Power management functions
- DC-DC converters
- Industrials

30V N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

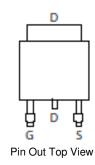
Mechanical Data

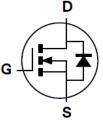
- Package: TO252
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ©3
- Terminal Connections: See Diagram
- Weight: 0.33 grams (Approximate)



TO252 (DPAK)

Top View





Equivalent Circuit

Ordering Information (Note 4)

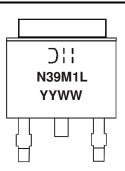
Part Number		Package	Packing		
	Part Nulliber	Fackage	Qty.	Carrier	
	DMN39M1LK3-13	TO252 (DPAK)	2,500	Tape & Reel	
Notes:	Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.				

EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



] | | = Manufacturer's Marking
 N39M1L = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 22 = 2022)
 WW = Week Code (01 to 53)

DMN39M1LK3 Document number: DS43800 Rev. 4 - 2



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	30	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current, $V_{GS} = 10V$ (Note 5)	Tc = +25°C Tc = +70°C	ID	89.3 71.4	А
Continuous Drain Current, V _{GS} = 10V (Note 6)	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	lo	17.9 14.3	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		ldм	357	А
Maximum Continuous Body Diode Forward Current (Note 6)	ls	3.6	А	
Pulsed Continuous Body Diode Forward Current (10µs Pulse,	lsм	357	А	
Avalanche Current, L = 0.1mH (Note 7)	las	41	Α	
Avalanche Energy, L = 0.1mH (Note 7)	E _{AS}	84	mJ	

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 8)	TA = +25°C	PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 8)	Steady State	Reja	85.4	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	PD	2.6	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Reja	47.1	°C/W
Total Power Dissipation (Note 5)	Tc = +25°C	PD	65.7	W
Thermal Resistance, Junction to Case (Note 5)	·	Rejc	1.9	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BVDSS	30	_	—	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current	IDSS		_	1	μA	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	lgss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	1	_	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-Resistance	Deserve	_	3.1	5.5	mΩ	VGS = 10V, ID = 30A	
Static Drain-Source On-Resistance	RDS(ON)	—	4.6	9.0	11122	V _{GS} = 4.5V, I _D = 15A	
Diode Forward Voltage	Vsd	_	0.7	1	V	$V_{GS} = 0V$, $I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	2253	—	pF		
Output Capacitance	Coss	—	304	—	pF	V _{DS} = 15V, V _{GS} = 0V - f = 1MHz	
Reverse Transfer Capacitance	Crss	_	230	_	pF		
Gate Resistance	Rg	_	2.4	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	—	19.3	—	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	38.6	_	nC		
Gate-Source Charge	Qgs	_	5.7	_	nC	V _{DS} = 15V, I _D = 15A	
Gate-Drain Charge	Q _{gd}	_	7.7	_	nC	7	
Turn-On Delay Time	tD(ON)	_	4.6	_	ns		
Turn-On Rise Time	tR	_	5.4	_	ns	V _{DD} = 15V, V _{GS} = 10V	
Turn-Off Delay Time	tD(OFF)	_	35.5	_	ns	R _G = 3.3Ω, I _D = 15A	
Turn-Off Fall Time	tF		15.7	_	ns		
Reverse Recovery Time	trr	_	16.6	—	ns		
Reverse Recovery Charge	Qrr	_	7.1	_	nC	I _F = 15A, dl/dt = 100A/μs	

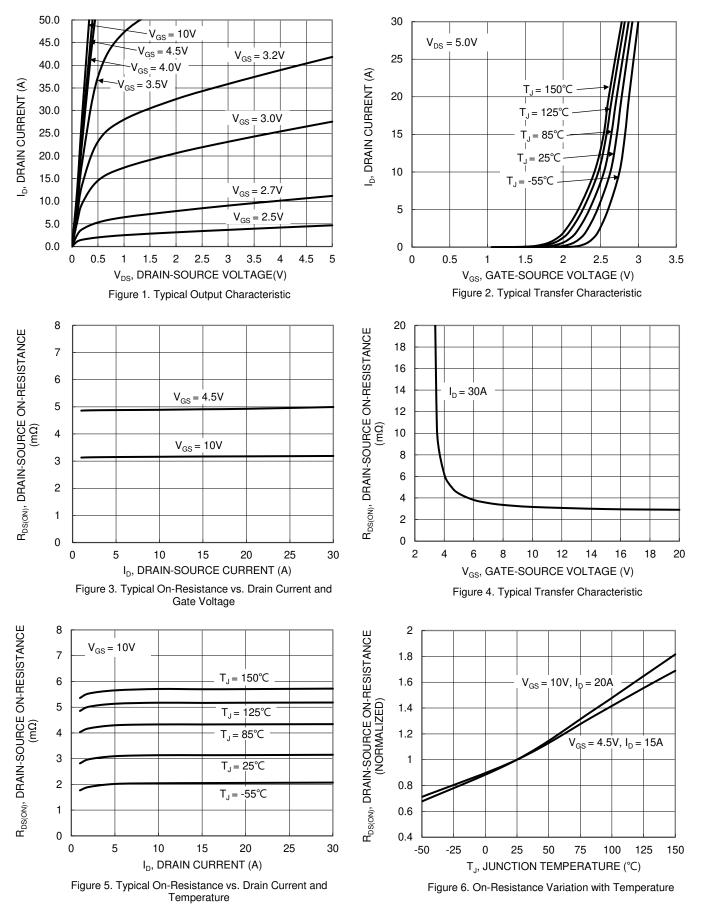
Notes:

5. Thermal resistance from junction to soldering point (on the exposed drain pad).
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
8. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.



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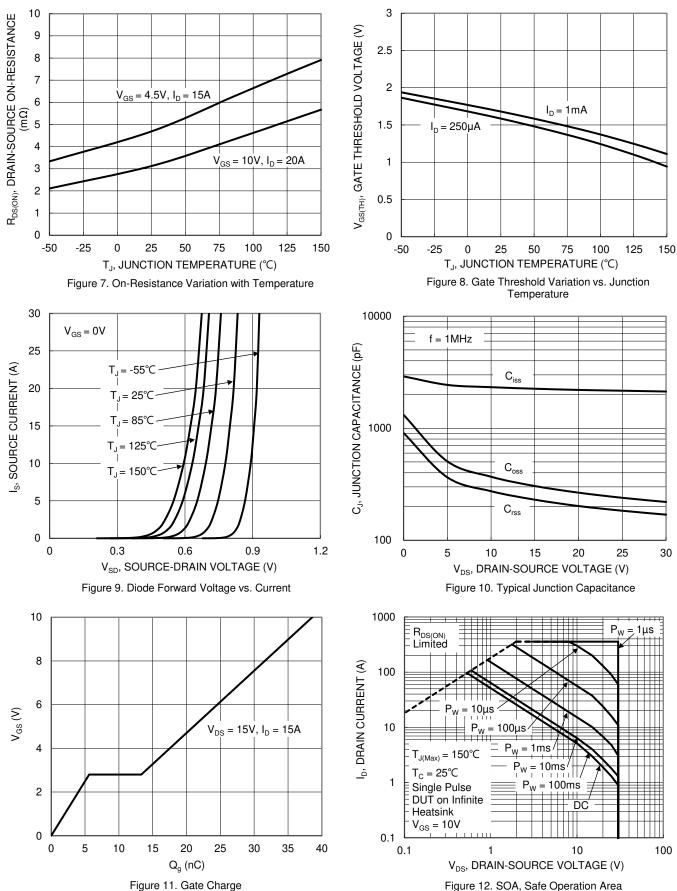


Figure 11. Gate Charge



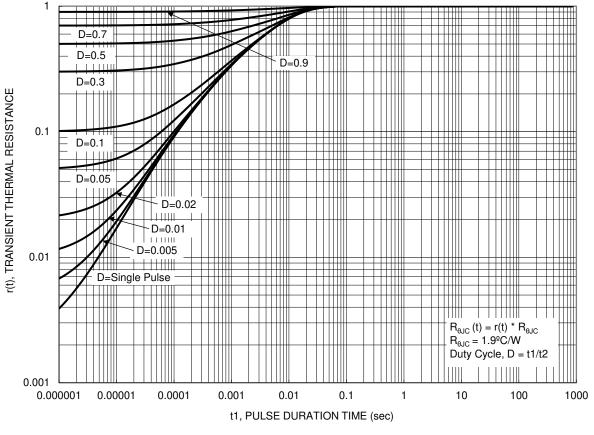
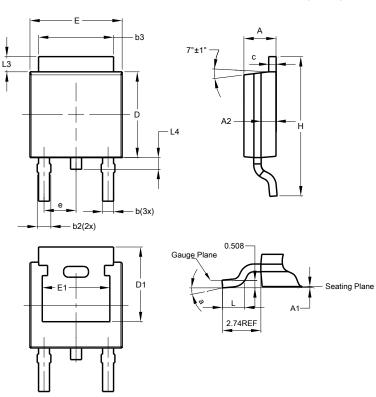


Figure 13. Transient Thermal Resistance



Package Outline Dimensions

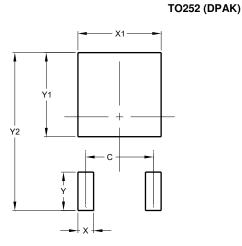
Please see http://www.diodes.com/package-outlines.html for the latest version.



	TO252 (DPAK)						
Dim	Min	Max	Тур				
Α	2.19	2.39	2.29				
A1	0.00	0.13	0.08				
A2	0.97	1.17	1.07				
b	0.64	0.88	0.783				
b2	0.76	1.14	0.95				
b3	5.21	5.50	5.33				
С	0.45	0.58	0.531				
D	6.00	6.20	6.10				
D1	5.21						
е	2.	286 BS	SC				
Е	6.45	6.70	6.58				
E1	4.32	-					
Н	9.40	10.41	9.91				
L	1.40	1.78	1.59				
L3	0.88	1.27	1.08				
L4	0.64	1.02	0.83				
а	0°	10°					
All	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.572
Х	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

TO252 (DPAK)



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